

## ABSTRACT OF THE DISCLOSURE

An apparatus including a support substrate comprising a plurality of first support contacts and a plurality of second support contacts on a surface of the support substrate; a chip comprising a plurality of circuits coupled to respective ones of a plurality of externally accessible chip contacts, wherein the chip contacts are coupled to respective ones of the first support contacts; a plurality of fusible masses coupled to respective ones of the plurality of second support contacts; an electrically-insulating encapsulant on the support substrate and the chip. A method including forming a plurality of fusible masses on respective ones of a plurality of externally accessible support contacts on a surface of a support substrate, the substrate further comprising a circuit structure on the surface; and encapsulating a portion of the support substrate and the circuit structure with an electrically insulating encapsulant.